



## Material Content Data Sheet



<b>Sales Product Name</b>				IPC100N04S5-1R9		<b>Issued</b>		1. August 2018	
<b>MA#</b>				MA001369330					
<b>Package</b>				PG-TDSON-8-34		<b>Weight*</b>		112.36 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.821	0.73	0.73	7305	7305	
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		142		
	non noble metal	iron	7439-89-6	0.053	0.05		474		
	non noble metal	copper	7440-50-8	53.151	47.30	47.36	473056	473672	
	noble metal	gold	7440-57-5	0.044	0.04	0.04	392	392	
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	392	392	
encapsulation	organic material	carbon black	1333-86-4	0.076	0.07		674		
	plastics	epoxy resin	-	5.979	5.32		53216		
	inorganic material	silicondioxide	60676-86-0	31.788	28.29	33.68	282921	336811	
leadfinish	non noble metal	tin	7440-31-5	1.574	1.40	1.40	14007	14007	
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1862	1862	
solder	non noble metal	tin	7440-31-5	0.023	0.02		206		
	noble metal	silver	7440-22-4	0.029	0.03		258		
	non noble metal	lead	7439-92-1	1.105	0.98	1.03	9837	10301	
CLIP plating	noble metal	silver	7440-22-4	0.639	0.57	0.57	5687	5687	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	iron	7439-89-6	0.017	0.02		150		
	non noble metal	copper	7440-50-8	16.828	14.98	15.00	149768	149963	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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